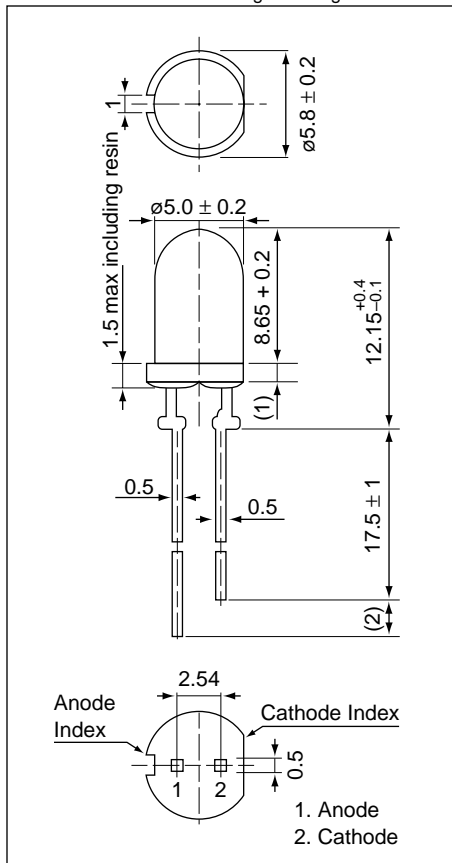




Weight: 0.31 g Unit: mm



## AND130BR

### GaAlAs Red Light Light Emission T-1 3/4 Package (5 mm)

#### Features

- Double hetero structure die
- Peak wavelength ( $\lambda_p = 660$  nm) high bright emission
- All plastic mold type, clear colorless lens
- Low drive current: 20 mA for outdoor applications  
0.5 mA for indoor applications
- Excellent On-Off contrast ratio
- Fast response time, capable of pulse operation
- Suitable for Outdoor Message Signboards

#### Maximum Ratings (T = 25°C)

| Characteristics             | Symbol    | Rating     | Unit |
|-----------------------------|-----------|------------|------|
| Forward Current             | $I_F$     | 50         | mA   |
| Reverse Voltage             | $V_R$     | 4          | V    |
| Power Dissipation           | $P_D$     | 125        | mW   |
| Operating Temperature Range | $T_{Opr}$ | -20 to 85  | °C   |
| Storage Temperature Range   | $T_{Stg}$ | -30 to 100 | °C   |

#### Electro-Optical Characteristics (T = 25°C)

| Characteristics          | Symbol          | Test Condition   | Minimum | Typical | Maximum | Unit    |
|--------------------------|-----------------|------------------|---------|---------|---------|---------|
| Forward Voltage          | $V_F$           | $I_F = 20$ mA    | —       | 1.85    | 2.4     | V       |
| Reverse Current          | $I_R$           | $V_R = 4$ V      | —       | —       | 50      | $\mu$ A |
| Luminous Intensity       | $I_V$           | $I_F = 20$ mA    | 560     | 1,280   | —       | mcd     |
| Peak Emission Wavelength | $\lambda_p$     | $I_F = 20$ mA    | —       | 660     | —       | nm      |
| Spectral Line Half Width | $\Delta\lambda$ | $I_F = 20$ mA    | —       | 15      | —       | nm      |
| Dominant Wavelength      | $\lambda_d$     | $I_F = 20$ mA    | —       | 640     | —       | nm      |
| Full Viewing Angle       | $\theta$        | $I_V = 1/2$ Peak | —       | 16      | —       | degree  |

#### Precaution

Please be careful of the following:

1. Soldering temperature: 260°C max  
Soldering time: 3 sec. max  
Soldering portion of lead: up to 2 mm from the body of the device
2. The lead can be formed up to 5 mm from the body of the device without forming stress.  
Soldering should be performed after the lead forming.

